



do NOT float (2V to 8V)
here max 4.6V

optional input filter -20dB

NOTES:
1) R19 for test purposes only

ASSEMBLY:
C11b to C15b backpaked
L2 does not meet pattern

Revision History	
Revision	Notes
A	*** preliminary ***
B	loop/snubber/HS-FET/Cin
C	added input filter vs reflected ripple

Designed for: Public Release	Mod. Date: 1/20/2015
Project Title: Telecom Buck Converter w/ TPS40170	
Sheet Title:	
Number: PMP10117	Rev: C
SVN Rev: Not in version control	Assembly Variant: Variant name not interpreted
Drawn By:	File: PMP10117RevC.SchDoc
Engineer: B.Geck	Contact: http://www.ti.com/support
Sheet: 1 of 1	
Size: A4	

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